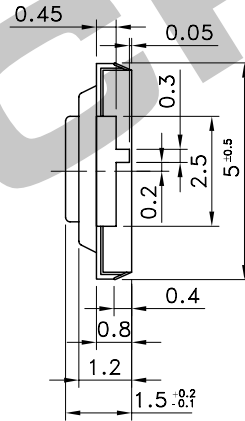
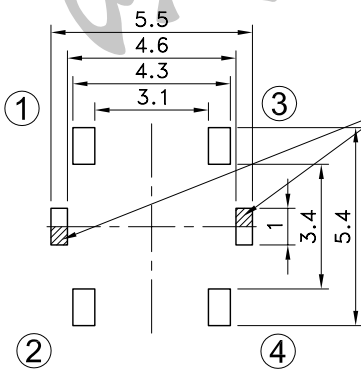


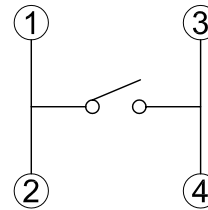
P.C.B TERMINAL POSITION



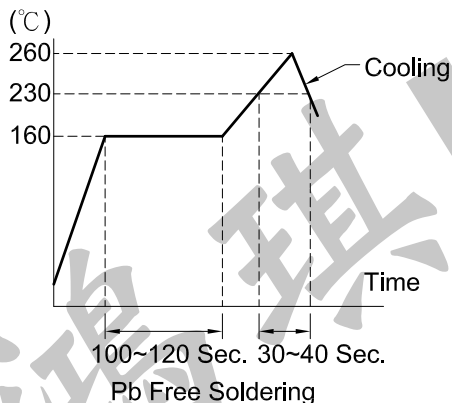
CIRCUIT ARRANGEMENT



GROUND PIN:
 The thickness of cream solder: 150~200 μ
 We recommend to connect the GND land shown in the switch spec. with the GND of your P.C.B for withstanding electric-static discharge.



REFLOW SOLDERING CONDITIONS



SPECIFICATIONS

- | | |
|-----------------------------|---|
| 1. Rating | : DC 15V 20mA |
| 2. Contact Resistance | : 50m Ω Max. |
| 3. Insulation Resistance | : 50M Ω Min. at DC 100V |
| 4. Dielectric Strength | : AC 250V For 1 Minute |
| 5. Operating Force | : 100 \pm 50gf |
| 6. Stroke | : 0.25 $^{+0.1}$ mm |
| 7. Life | : 1,000,000 Cycles |
| 8. Taping | : 5,000 Pcs/Reel |
| 9. Reflow Soldering Profile | : According Reflow Profile Max. 2 Times |

REVISION:		DATE:		REVISION:		DATE:	
UNIT:mm		THIRD ANGLE PROJECTION METHOD		TOL. UNLESS OTHERWISE STATED: ± 0.3		CODE NO.:HCH-135-4	
ISSUED		CONFIRMED		 HCH [®] HORNG CHIH ISO9001 Certified ISO14001 Certified 鴻琪股份有限公司		PART NO.	
John 2007.05.18		Elvis 2007.05.18				STS-05	